

Title (en)
CERAMIC PRINTED CIRCUIT BOARD COMPRISING AN AL COOLING BODY

Title (de)
KERAMISCHE LEITERPLATTE MIT AL-KÜHLKÖRPER

Title (fr)
CARTE DE CIRCUITS IMPRIMÉS EN CÉRAMIQUE POURVUE D'UN DISSIPATEUR THERMIQUE EN ALUMINIUM

Publication
EP 2695189 A1 20140212 (DE)

Application
EP 12714276 A 20120330

Priority
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Abstract (en)
[origin: WO2012136579A1] The invention relates to a ceramic printed circuit board (2) comprising an upper side (2a) and a lower side (2b), sintered metallisation regions being arranged on the upper side (2a), and the lower side being embodied as a cooling body (3). In order to improve the heat dissipation of components on the upper side of the printed circuit board, the lower side (2b) is also provided with sintered metallisation regions to which a metal cooling body (3) is soldered.

IPC 8 full level
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CPC (source: EP KR US)
F21V 29/00 (2013.01 - KR); **F21V 29/508** (2015.01 - US); **F21V 29/80** (2015.01 - EP US); **F21V 29/86** (2015.01 - EP US); **F21V 29/89** (2015.01 - US); **H01L 23/367** (2013.01 - KR); **H01L 23/3677** (2013.01 - EP US); **H01L 23/373** (2013.01 - KR); **H01L 23/3735** (2013.01 - EP US); **H05K 1/0201** (2013.01 - US); **H05K 1/0203** (2013.01 - EP US); **H05K 3/0061** (2013.01 - EP US); **F21Y 2115/10** (2016.07 - EP US); **H01L 33/642** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US); **H05K 1/0306** (2013.01 - EP US); **H05K 2201/10106** (2013.01 - EP US)

C-Set (source: EP US)
H01L 2924/0002 + H01L 2924/00

Citation (search report)
See references of WO 2012136579A1

Citation (examination)
US 6543521 B1 20030408 - SATO KAORU [JP], et al

Designated contracting state (EPC)
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DOCDB simple family (publication)
DE 102012205178 A1 20121004; BR 112013025429 A2 20161227; CN 103563074 A 20140205; CN 103563074 B 20180914; EP 2695189 A1 20140212; JP 2014517497 A 20140717; KR 20140034781 A 20140320; RU 2013148615 A 20150510; TW 201302046 A 20130101; US 2014016330 A1 20140116; US 9730309 B2 20170808; WO 2012136579 A1 20121011

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